

Title (en)

Water-soluble material, chemically amplified resist and pattern formation method using the same

Title (de)

Wasserlösliches Material, chemisch verstärkter Resist, und Bilderzeugungsverfahren unter Verwendung dieses Resists

Title (fr)

Matière soluble dans l'eau, réserve chimiquement amplifiée, et procédé de formation d'images employant cette réserve

Publication

EP 1553453 A2 20050713 (EN)

Application

EP 04029999 A 20041217

Priority

JP 2003425071 A 20031222

Abstract (en)

A water-soluble material used for forming a water-soluble film on a chemically amplified resist film includes a water-soluble polymer, an acid generator and a compound constructing an inclusion compound for incorporating the acid generator. Also, in a pattern formation method, a chemically amplified resist film is formed on a substrate, and a water-soluble film made of a water-soluble material including a water-soluble polymer, an acid generator and a compound constructing an inclusion compound for incorporating the acid generator is formed on the resist film. Thereafter, pattern exposure is carried out by selectively irradiating the resist film with exposing light through the water-soluble film, the resultant resist film is developed and the water-soluble film is removed. Thus, a resist pattern made of the resist film is formed.

IPC 1-7

G03F 7/095; G03F 7/004

IPC 8 full level

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CPC (source: EP US)

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